

ABSTRACT OF THE DISCLOSURE

A processing apparatus is used for processing a workpiece such as a semiconductor wafer. The processing apparatus comprises a cover for covering a portion of a surface, to be processed, of a workpiece, a process chamber formed by the cover and the surface, to be processed, of the workpiece, and a sealing portion provided between the cover and the surface of the workpiece for sealing the process chamber.

10

20250707 10:40:00